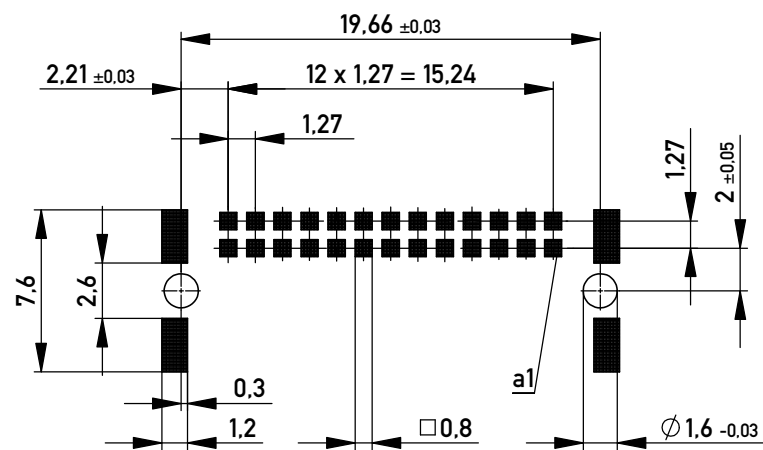


**Leiterplatten-Layout Vorschlag für SMT**  
**PCB-Layout Proposal for SMT**



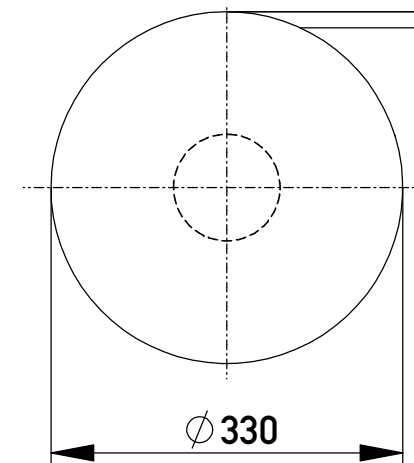
Anforderungsstufe 1  
Performance Level 1

Kontaktbereich vergoldet  
Mating Area gold plating

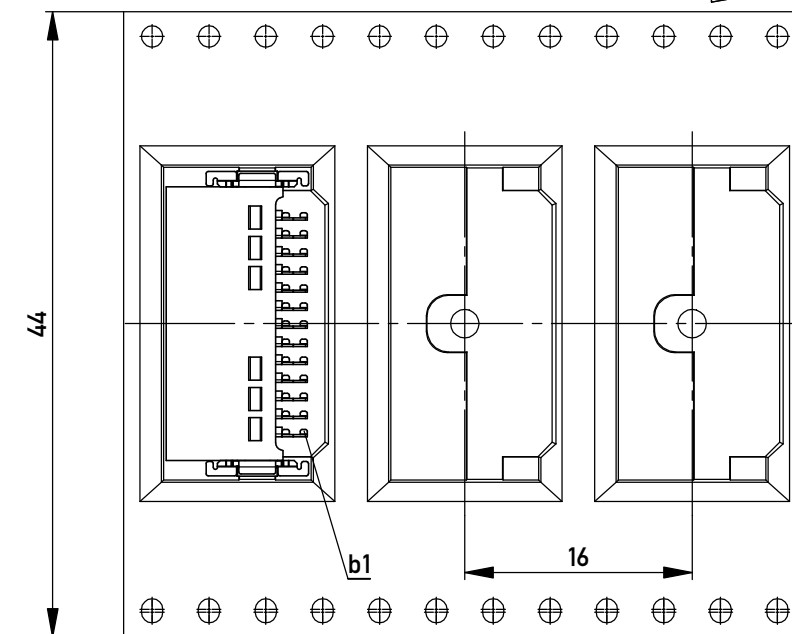
Anschlussbereich verzinkt 4-6 µm  
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm  
Coplanarity Area of Termination ≤ 0,1 mm

Verpackt im Gurt in Anlehnung an DIN IEC 60286-3  
Tape on Reel Packaging according to DIN IEC 60286-3  
Verpackungseinheit: 560 Stück  
Packaging unit: 560 pcs



**Abspulrichtung - Reel off Direction**



BA3-03 - Standard Bauhöhe  
type3-03 - Standard Assembly Height

Information:	Tolerances	 All Dimensions in mm	Scale	3:1
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Subject to modification without prior notice. Drawing will not be updated.		 www.ERNI.com	<b>054595</b>	
g	28.02.2017		Class SMCB	
Index	Date	i A3		

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